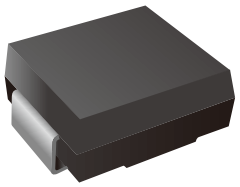
领晨科技
LEADING-TECH

LTU5AC THRU LTU5MC

Surface Mount Ultra Fast Recovery Rectifier

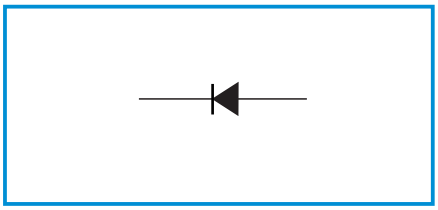
Reverse Voltage - 50~1000V
Forward Current - 5A



Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

Functional Diagram



Mechanical Data

- **Case**: SMC
- **Terminals**: Solder plated, solderable per MIL-STD-750, Method 2026
- **Approx Weight**:217mg /0.0077oz
- **Polarity**: Color band denotes cathode end

Maximum Ratings And Electrical Characteristics

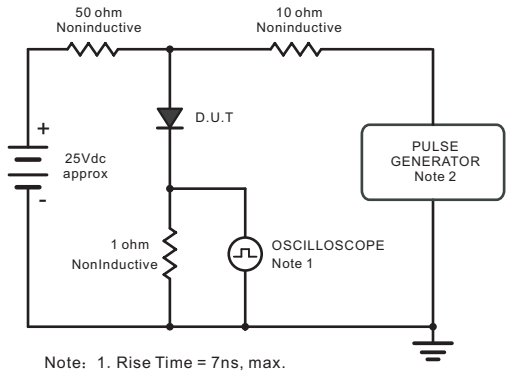
Ratings at 25 °C ambient temperature unless otherwise specified.
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	LTU5AC	LTU5BC	LTU5DC	LTU5GC	LTU5JC	LTU5KC	LTU5MC	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T_c = 100 °C	$I_{F(AV)}$	5							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	120							A
Maximum Instantaneous Forward Voltage at 5 A	V_F	1.0			1.3	1.65			V
Maximum DC Reverse Current T_a = 25 °C at Rated DC Blocking Voltage T_a =125 °C	I_R	5 100							μA
Typical Junction Capacitance at V_R=4V, f=1MHz	C_j	50							pF
Maximum Reverse Recovery Time (1)	t_{rr}	50				75			ns
Typical Thermal Resistance (2)	$R_{\theta JA}$	35							°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							°C

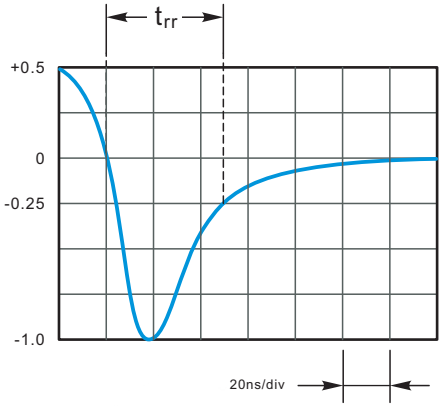
(1) Measured with I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A.
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Ratings And Characteristic Curves

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm,22pF.
2. Ries Time =10ns, max.
Source Impedance = 50 ohms.



Set time Base for 20ns/div

Fig.2 Maximum Average Forward Current Rating

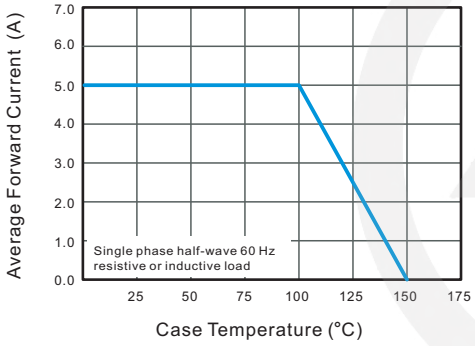


Fig.3 Typical Reverse Characteristics

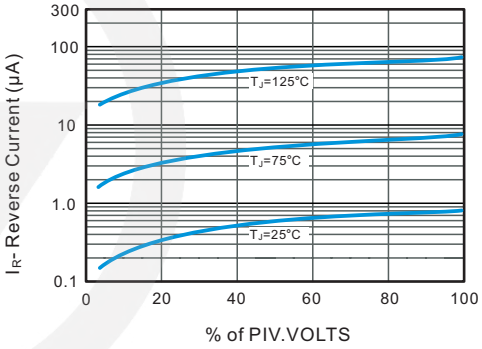


Fig.4 Typical Forward Characteristics

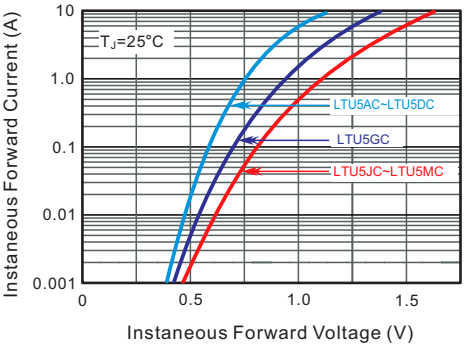


Fig.5 Typical Junction Capacitance

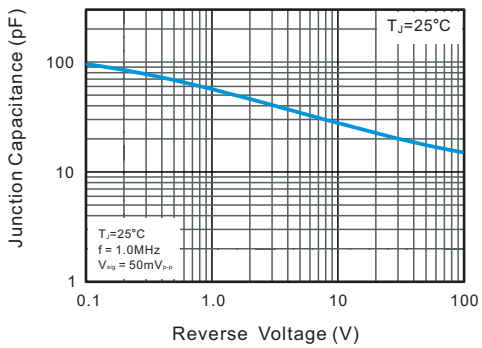
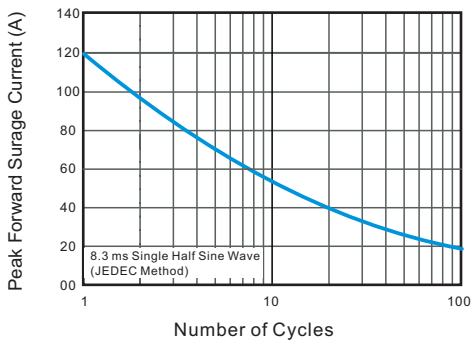
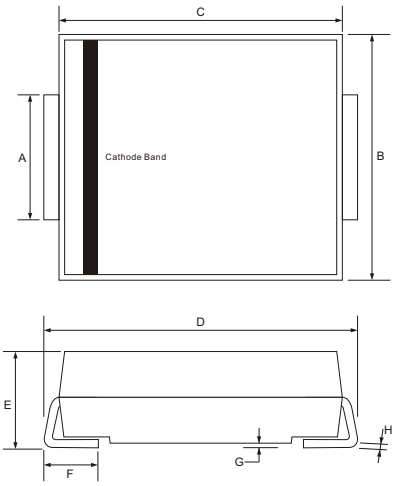


Fig.6 Maximum Non-Repetitive Peak Forward Surage Current



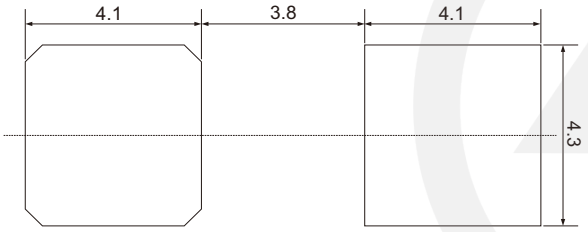
SMC Package Outline



Unit : mm

SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	2.75	3.27
B	5.59	6.22
C	6.50	7.11
D	7.60	8.13
E	1.99	2.61
F	0.76	1.60
G	0.05	0.31
H	0.10	0.31

SMC Suggested Pad Layout



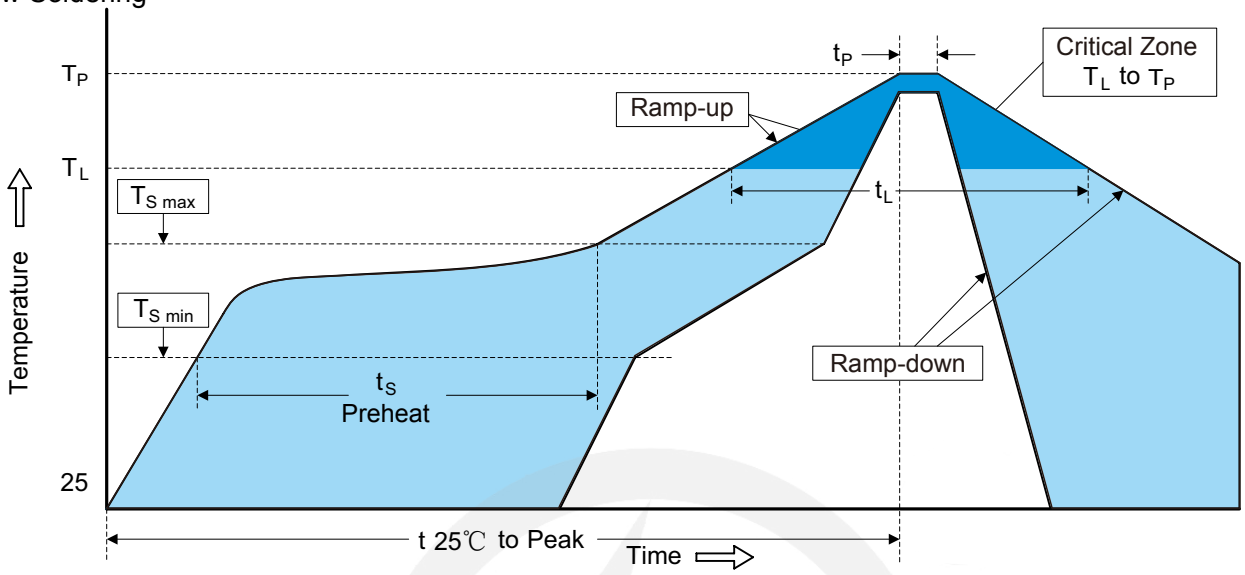
Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm
3.The pad layout is for reference purpose only.

Marking

Type number	Marking code
LTU5AC	US5A
LTU5BC	US5B
LTU5DC	US5C
LTU5GC	US5G
LTU5JC	US5J
LTU5KC	US5K
LTU5MC	US5M

Recommended Soldering Conditions

Reflow Soldering

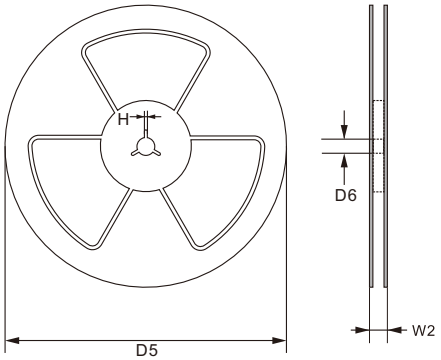


Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3℃/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_S)	 150℃ 200℃ 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	 3℃/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	 217℃ 60-150 seconds
Peak Temperature (T_P)	260℃
Time within 5℃ of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8 minutes max.

Packaging

13” Reel



D5	Φ330.0±2.0
D6	Φ13.5±0.5
H	2.5±1.0
W2	16.0±2.0
Quantity: 3000PCS	